



N-Channel 20-V (D-S) 175°C MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A) ^a	Q_g (Typ)
20	0.012 @ $V_{GS} = 10$ V	40 ^a	7.5
	0.026 @ $V_{GS} = 4.5$ V	40 ^a	

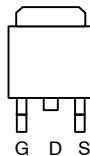
FEATURES

- TrenchFET® Power MOSFET
- 175°C Junction Temperature
- Optimized for High-Side Synchronous Rectifier
- 100% R_g Tested

APPLICATIONS

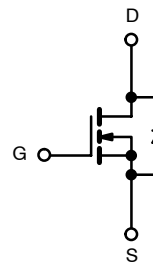
- Desktop or Server CPU Core
- Game Station

TO-263



Top View

DRAIN connected to TAB



N-Channel MOSFET

Ordering Information: SUM40N02-12P
SUM40N02-12P—E3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 175^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	40 ^a	A
	$T_C = 100^\circ\text{C}$		40 ^a	
Pulsed Drain Current		I_{DM}	90	
Maximum Power Dissipation ^b	$T_C = 25^\circ\text{C}$	P_D	83 ^c	W
	$T_A = 25^\circ\text{C}$ ^d		3.75	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mounted) ^d	R_{thJA}	40	$^\circ\text{C/W}$
Junction-to-Case	R_{thJC}	1.8	

Notes

- Package limited.
- Duty cycle $\leq 1\%$.
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS (T_J = 25 °C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{DS} = 0 V, I _D = 250 μA	20			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	0.85	2	3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	μA
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 125°C			50	
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 175°C			250	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	90			A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		0.0095	0.012	Ω
		V _{GS} = 10 V, I _D = 20 A, T _J = 125°C			0.0175	
		V _{GS} = 10 V, I _D = 20 A, T _J = 175°C			0.022	
		V _{GS} = 4.5 V, I _D = 15 A		0.021	0.026	
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 20 A	10			S
Dynamic ^b						
Input Capacitance	C _{iSS}	V _{GS} = 0 V, V _{DS} = 10 V, f = 1 MHz		1000		pF
Output Capacitance	C _{oSS}			370		
Reverse Transfer Capacitance	C _{rSS}			180		
Total Gate Charge ^b	Q _g	V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 40 A		7.5	12	nC
Gate-Source Charge ^b	Q _{gs}			3.5		
Gate-Drain Charge ^b	Q _{gd}			2.6		
Gate Resistance	R _g		1.5	3.0	5.1	Ω
Turn-On Delay Time ^b	t _{d(on)}	V _{DD} = 10 V, R _L = 0.25 Ω I _D ≅ 40 A, V _{GEN} = 10 V, R _g = 2.5 Ω		11	20	ns
Rise Time ^b	t _r			10	15	
Turn-Off Delay Time ^b	t _{d(off)}			24	35	
Fall Time ^b	t _f			9	15	
Source-Drain Diode Ratings and Characteristics (T _C = 25 °C) ^c						
Continuous Current	I _S				40	A
Pulsed Current	I _{SM}				90	
Forward Voltage ^a	V _{SD}	I _F = 40 A, V _{GS} = 0 V		1.1	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 40 A, di/dt = 100 A/μs		20	40	ns
Peak Reverse Recovery Current	I _{RM}			0.7	1.1	A
Reverse Recovery Charge	Q _{rr}			0.007	0.022	μC

Notes

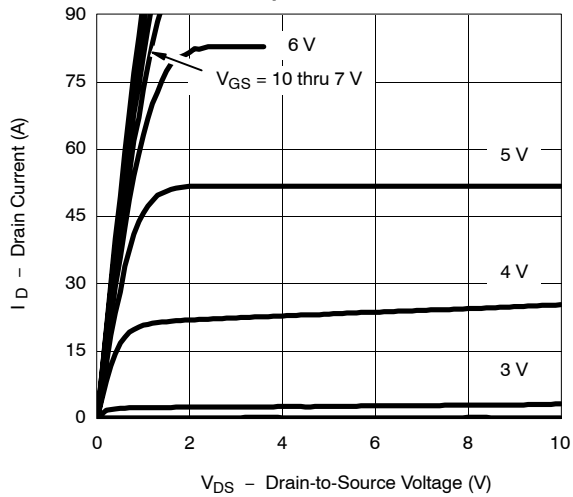
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. Independent of operating temperature.
c. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

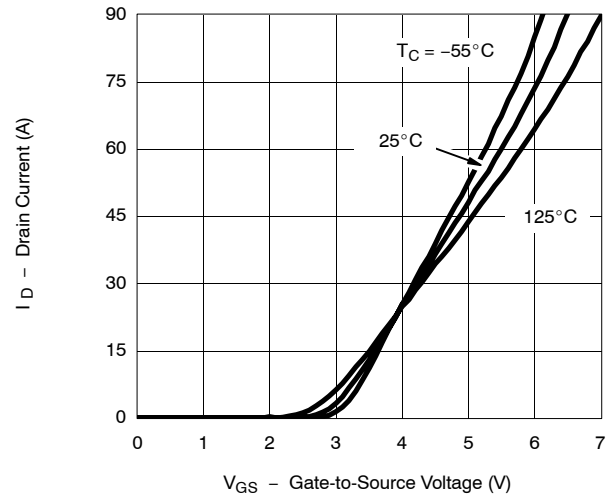


TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

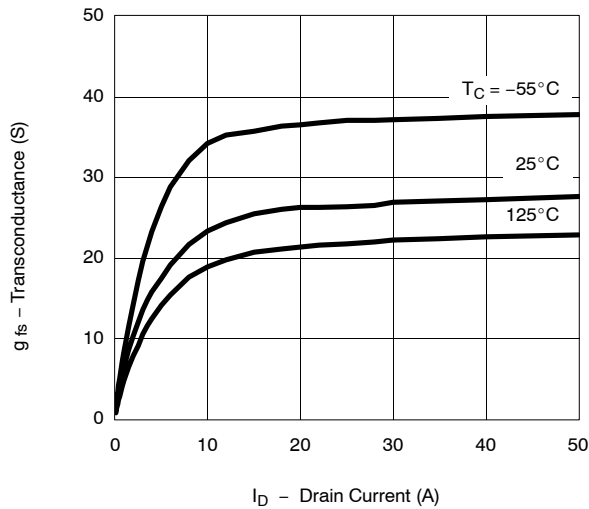
Output Characteristics



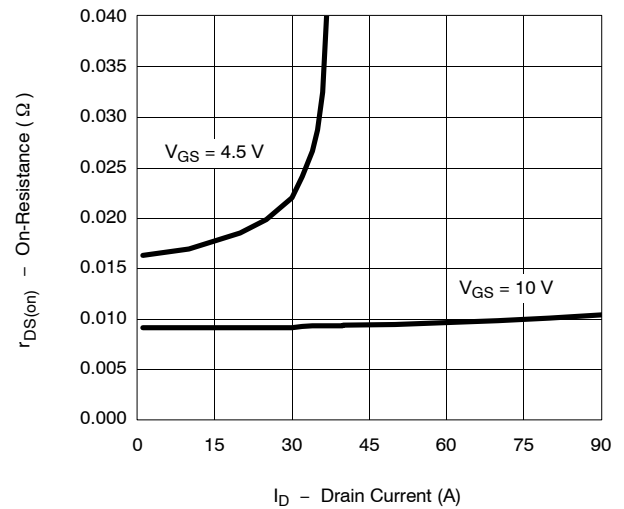
Transfer Characteristics



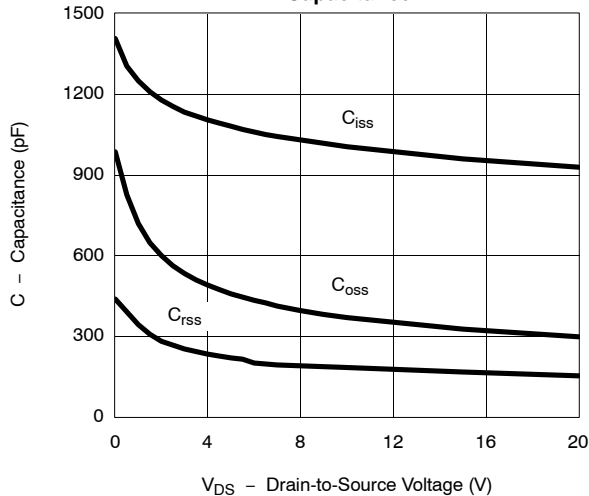
Transconductance



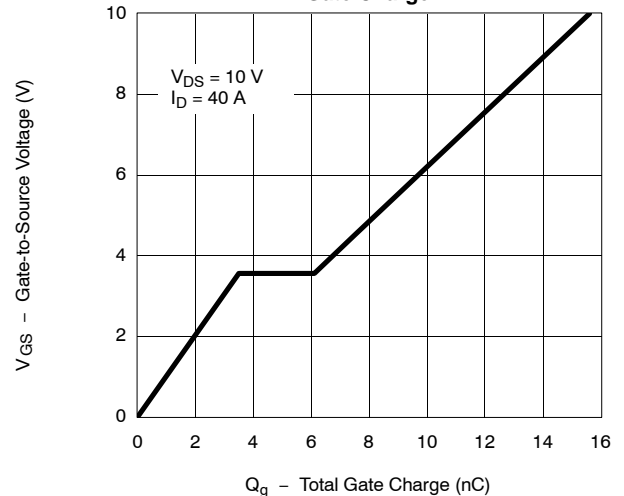
On-Resistance vs. Drain Current

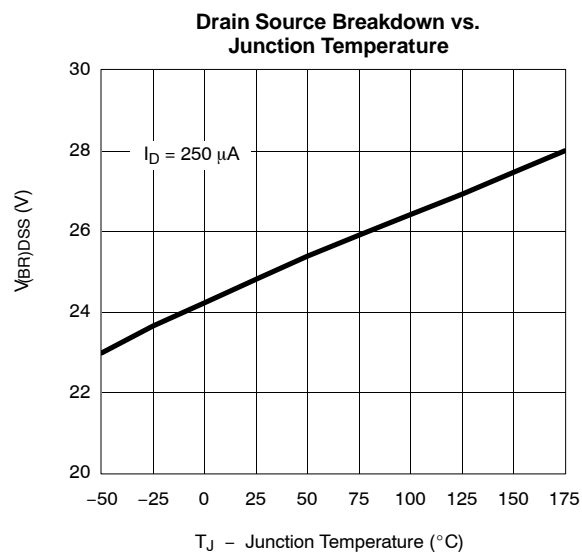
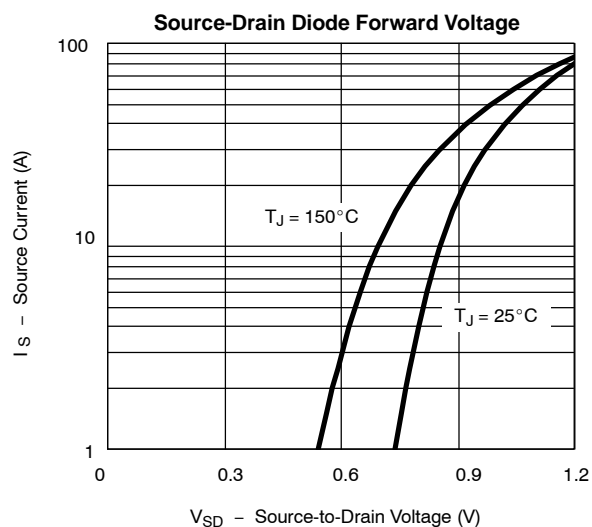
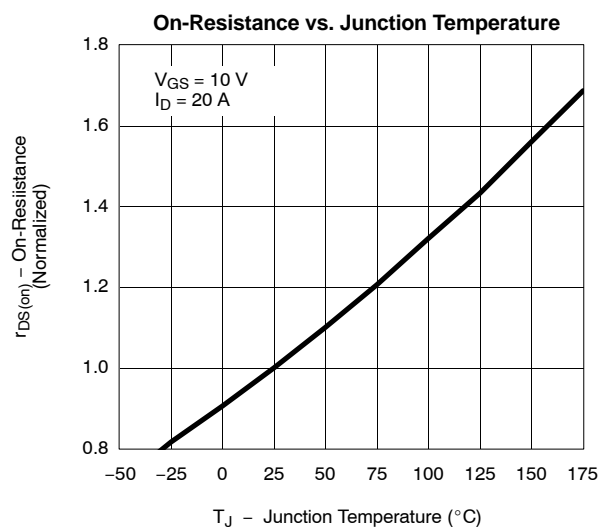


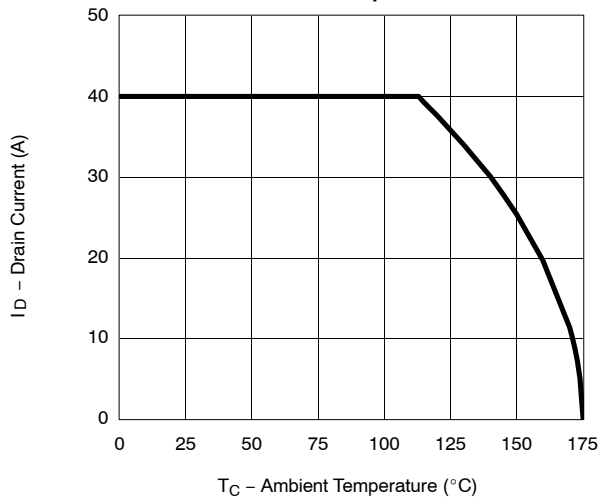
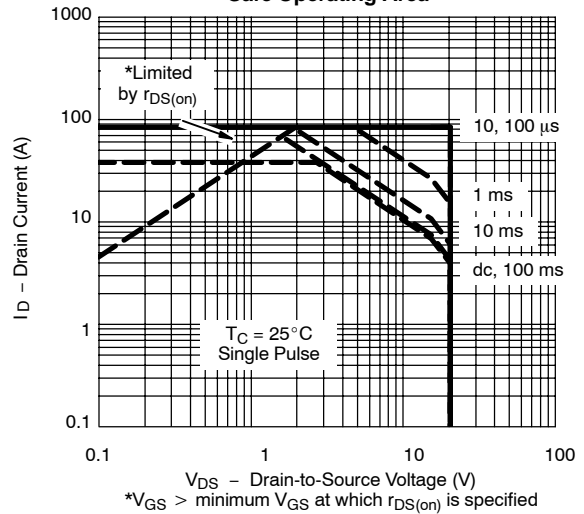
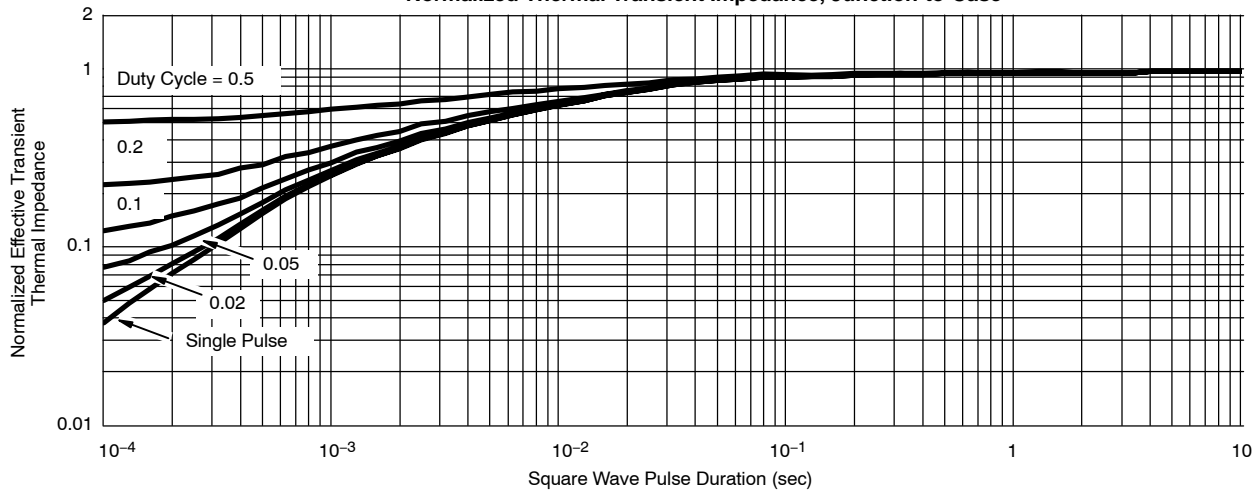
Capacitance



Gate Charge



TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

**THERMAL RATINGS****Maximum Avalanche and Drain Current
vs. Case Temperature****Safe Operating Area****Normalized Thermal Transient Impedance, Junction-to-Case**

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